

Appl. No. 10/817,195
Amdt. dated January 22, 2006
Reply to Office Action of October 24, 2006

PATENT

Amendments to the Specification:

Please replace paragraph [0003] with the following amended paragraph:

[0001] FIG. 1 shows a cross section of a conventional optocoupler DIP package 10. The illustrated optocoupler 10 includes a lead frame 24 comprising leads 24(a), 24(b) (i.e., pins). An optical emitter device 12 is mounted on one lead 24(a). An optical receiver device 14 is mounted on the other lead 24(b). The optical receiver device 14 generates an electrical signal after receiving light 20 generated by the optical emitter device 12. The optical emitter device 12 is electrically coupled to the lead 24(a) through its bottom surface, and to another lead (not shown) via a wire 11. Similarly, optical receiver device 14 is electrically coupled to the lead 24(b) through the bottom surface and to another lead (not shown) via a wire 13. It will be recognized by those skilled in the art that the optical emitter device 12 operates with two electrical connections, an anode and a cathode. These connections are thus provided by the wire 11 and the lead 24(a). Similarly, optical receiver device 14 operates with two electrical connections, typically an emitter and a collector. These connections are provided by the wire 13 and lead 24(b). The optocoupler package 10 further includes an optically transmissive medium 16. A molding compound 18 encases the leadframe 24, optical emitter device 12, optical receiver device 14, and the optically transmissive medium 16.